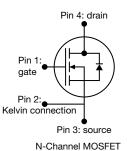
Vishay Siliconix

E Series Power MOSFET





PRODUCT SUMMARY					
V_{DS} (V) at T_J max.	65	50			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.120			
Q _g max. (nC)	4	4			
Q _{gs} (nC)	11				
Q _{gd} (nC)	8	3			
Configuration	Sin	gle			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and halogen-free	SiHH120N60E-T1-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	600	V
Gate-source voltage			V _{GS}	± 30	_ V
Continuous drain current (T _J = 150 °C)	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	24	
	V _{GS} at 10 V	T _C = 100 °C		15	Α
Pulsed drain current ^a			I _{DM}	57	
Linear derating factor				1.25	W/°C
Single pulse avalanche energy b			E _{AS}	56	mJ
Maximum power dissipation			P _D	156	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope $T_J = 125$ °C		125 °C	d. //d+	100	1//20
Reverse diode dv/dt ^c			dv/dt	50	V/ns

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 $\Omega,\,I_{AS}$ = 2 A
- c. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	42	55	°C/W
Maximum junction-to-case (drain)	R _{thJC}	0.57	0.80	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-source breakdown voltage	V_{DS}	V _{GS} =	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	ce to 25 °C, I _D = 1 mA	-	0.60	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	3.0	-	5.0	V
Onto anima lankana	_	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
7		V _{DS} =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 12 A	-	0.106	0.120	Ω
Forward transconductance	9 _{fs}	V_{DS}	= 20 V, I _D = 12 A	-	6.9	-	S
Dynamic					•	•	
Input capacitance	C _{iss}		$V_{GS} = 0 V$	-	1600	-	
Output capacitance	C _{oss}	,	$V_{DS} = 100 \text{ V},$	-	76	-	
Reverse transfer capacitance	C _{rss}		f = 1 MHz	-	6	-	
Effective output capacitance, energy related ^a	C _{o(er)}	., .,		-	57	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}	$V_{DS} = 0$	V to 480 V, V _{GS} = 0 V	-	355	-	
Total gate charge	Q _g			-	29	44	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 12 \text{ A}, V_{DS} = 480 \text{ V}$	-	11	-	nC
Gate-drain charge	Q _{gd}			-	8	-	
Turn-on delay time	t _{d(on)}			-	25	50	
Rise time	t _r	V _{DD} =	= 480 V, I _D = 12 A,	-	47	94	
Turn-off delay time	t _{d(off)}		= 10 V, $R_g = 9.1 \Omega$	-	38	78	ns
Fall time	t _f			-	29	58	
Gate input resistance	R _g		f = 1 MHz	0.32	0.63	1.26	Ω
Drain-Source Body Diode Characteristic	S						
Continuous source-drain diode current	I _S	MOSFET sym	ıbol	-	-	24	_
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	57	- A
Diode forward voltage	V _{SD}	T _J = 25 °C	C, I _S = 12 A, V _{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t _{rr}	-		-	343	686	ns
Reverse recovery charge	Q _{rr}		5 °C, I _F = I _S = 12 A,	-	5.6	11.2	μC
Reverse recovery current	I _{RRM}		$100 \text{ A/}\mu\text{s}, V_{\text{R}} = 400 \text{ V}$	-	30	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

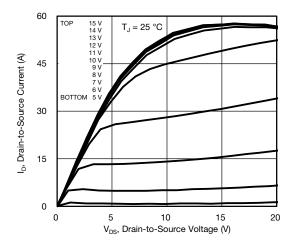


Fig. 1 - Typical Output Characteristics

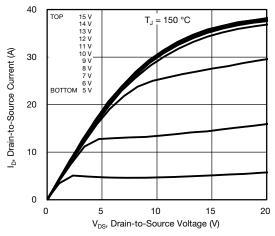


Fig. 2 - Typical Output Characteristics

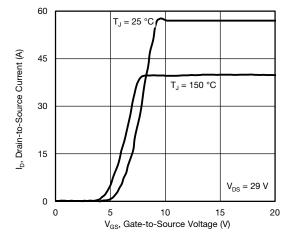


Fig. 3 - Typical Transfer Characteristics

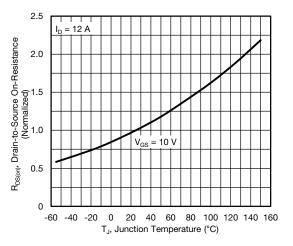


Fig. 4 - Normalized On-Resistance vs. Temperature

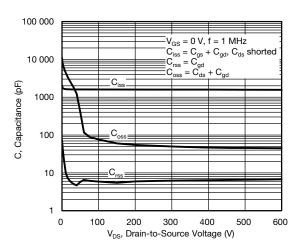


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

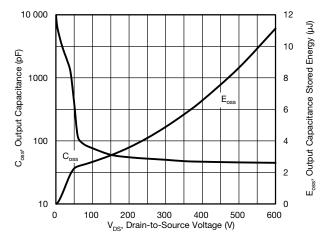


Fig. 6 - Coss and Eoss vs. V_{DS}



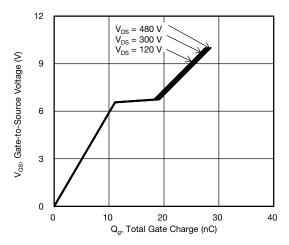


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

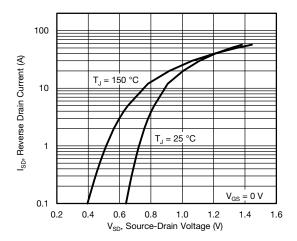


Fig. 8 - Typical Source-Drain Diode Forward Voltage

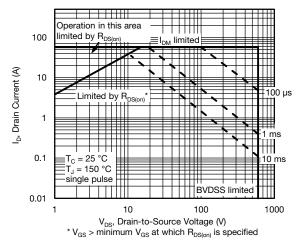


Fig. 9 - Maximum Safe Operating Area

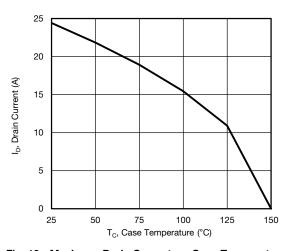


Fig. 10 - Maximum Drain Current vs. Case Temperature

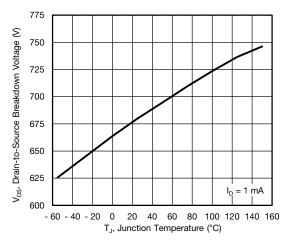


Fig. 11 - Temperature vs. Drain-to-Source Voltage



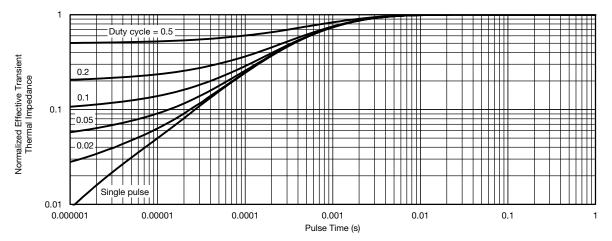


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

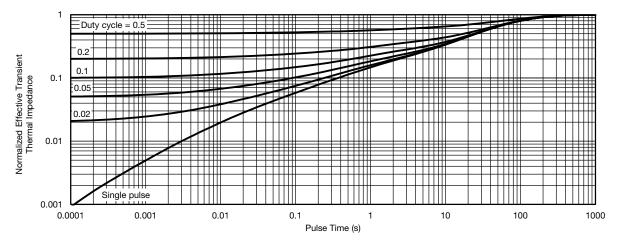


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

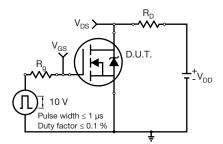


Fig. 14 - Switching Time Test Circuit

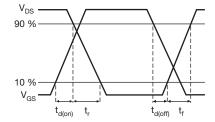


Fig. 15 - Switching Time Waveforms



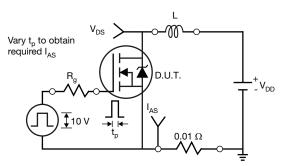


Fig. 16 - Unclamped Inductive Test Circuit

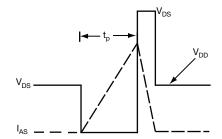


Fig. 17 - Unclamped Inductive Waveforms

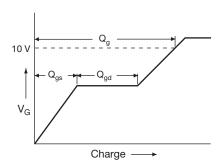


Fig. 18 - Basic Gate Charge Waveform

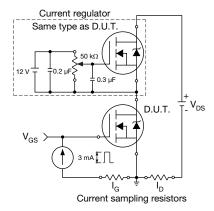
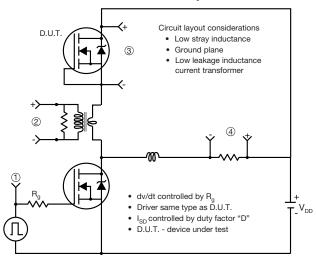


Fig. 19 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



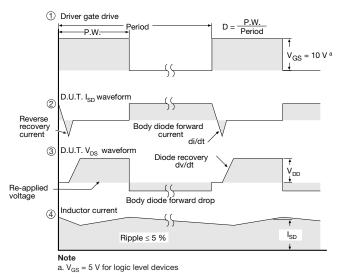


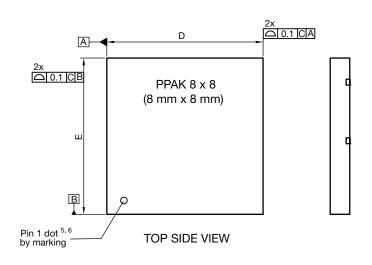
Fig. 20 - For N-Channel

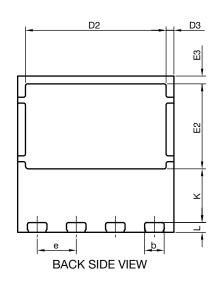
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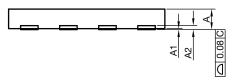


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PowerPAK® 8 x 8 Case Outline







DIM.	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2	020 ref.			0.008 ref.			
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3	0.40 BSC			0.016 BSC			
е	2.00 BSC		0.079 BSC				
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC			0.016 BSC			
K	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ⁽³⁾	8			8 8			

Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

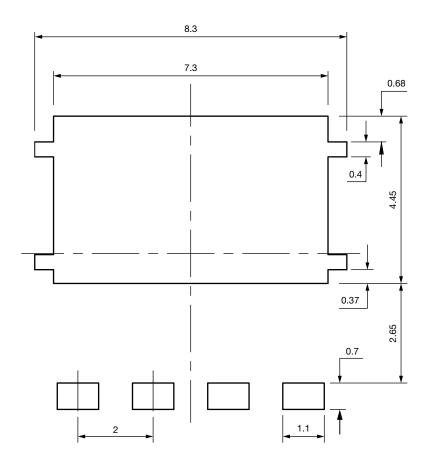
ECN: E20-0518-Rev. B, 28-Sep-2020

DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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